

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 2, line 19, to read as follows:

D1
In accordance with an embodiment of the present invention, an LOC type semiconductor package has leads of a lead frame shaped to accommodate semiconductor chips of different sizes and bond pad arrangements such as conventional single row and double row configurations. Accordingly, a change in semiconductor chip design that changes the size of a semiconductor chip does not require a new design for the lead frame. Accordingly, process changes or chip redesign are more efficient because less redesigning of the LOC package is required. Additionally, the same lead frame design can be used in different products that have different chip sizes, and the efficiency of mass production and reduced numbers of parts stocked for lead frames reduces the manufacturing costs of the products.

Please insert the following new paragraph on page 3, after line 25:

D2
FIG. 8 illustrates an LOC type semiconductor package in accordance with an embodiment of the invention incorporating a semiconductor chip having a conventional double row bond pad arrangement.

Please amend the paragraph on page 8, starting at line 6, to read as follows:

D3
As described above, the present invention modified the shapes of the leads to flexibly cope with variations in semiconductor chip size and bond pad arrangement. By doing so, semiconductor chips in various sizes or utilizing different bond pad arrangements can be mounted on the same leads. The present invention can be applied to a variety of kinds of LOC

D³ type semiconductor packages including, for example, multi-chip LOC type semiconductor [package] packages as well as the above-described LOC type semiconductor package, which includes a single chip.

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